

IN THE CLAIMS:

Please amend the claims as follows:

B1 1. (Twice Amended) A semiconductor device assembly, comprising:
a semiconductor die having an active surface having a plurality of bond pads thereon and an opposing second surface;
at least one projection connected to at least one bond pad of said plurality of bond pads on the active surface of said semiconductor die for direct connection to a substrate, said at least one projection including one of at least one solder ball and at least one solder bump; and
a generally centrally positioned paddle of a lead frame of a plurality of lead frames having side rails and cross members connected to said paddle, said second surface of said semiconductor die being secured to said paddle; and said generally centrally positioned paddle being attached to the side rail by at least a plurality of paddle support bars and being attached to said cross members by said support bars.

B2 5. (Amended) The semiconductor device assembly of claim 1, further comprising:
an electrically non-conductive adhesive layer securing said second surface to said generally centrally positioned paddle.

B3 7. (Amended) The semiconductor device assembly of claim 1, further comprising:
an electrically conductive adhesive layer securing said second surface of said semiconductor die to said generally centrally positioned paddle.

B4 14. (Twice Amended) A semiconductor device assembly, comprising:
a semiconductor die having an active surface having at least one bond pad thereon and an opposing second surface;

at least one projection secured to said at least one bond pad on said active surface of said semiconductor die for direct connection to a substrate, said at least one projection including one of at least one solder ball and at least one solder bump; and a metal paddle from a lead frame, said second surface of said semiconductor die being attached to said metal paddle; and said metal paddle is attached to at least one side rail by at least a plurality of paddle support bars and being attached to a plurality of cross members by said support bars.

27. (Twice Amended) A semiconductor device assembly, comprising:
a semiconductor die having an active surface having a plurality of bond pads thereon and an opposing second surface;
a plurality of projections connected to said plurality of bond pads for direct connection to a host circuit board, said plurality of projections including one of a plurality of solder balls and a plurality of solder bumps; and
a metallic paddle secured to said second surface of said semiconductor die, said metallic paddle being attached to at least one side rail by at least a plurality of paddle support bars and being attached to a plurality of cross members by said support bars.